- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

These devices contain two independent $J-\overline{K}$ positive-edge-triggered flip-flops. A low level at the preset or clear inputs sets or resets the outputs regardless of the levels of the other inputs. When preset and clear are inactive (high), data at the J and \overline{K} inputs meeting the setup time requirements are transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold time interval, data at the J and \overline{K} inputs may be changed without affecting the levels at the outputs. These versatile flip-flops can perform as toggle flip-flops by grounding \overline{K} and tying J high. They also can perform as D-type flip-flops if J and \overline{K} are tied together.

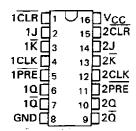
The SN54109 and SN54LS109A are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74109 and SN74LS109A are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each flip-flop)

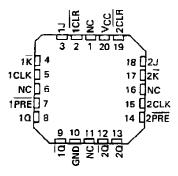
	IN	PUTS			OUT	PUTS
PRE	CLR	CLK	J	K	a	ā
L	Н	X	х	Х	H	L
н	L	×	X	X	L	Н
L	L	X	Х	Х	Нţ	Нţ
Н	н	f	L	L	L	Н
Н	H	t	Н	L	TOGG	GLE
н	Н	Ť	Ł	н	വു	$\overline{\alpha}_0$
н	Н	t	Н	н	H	L
н	н	L	Х	х	Q ₀	ō₀ ·

 $^{^\}dagger$ The output levels in this configuration are not guaranteed to meet the minimum levels for V_{OH} if the lows at preset and clear are near V_{1L} maximum. Furthermore, this configuration is nonstable; that is, it will not persist when preset or clear return to their inactive (high) level.

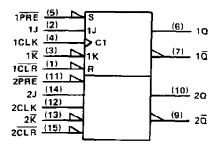
SN54109, SN54LS109A...J OR W PACKAGE SN74109...N PACKAGE SN74LS109A...D OR N PACKAGE (TOP VIEW)



SN54LS109A ... FK PACKAGE (TOP VIEW)



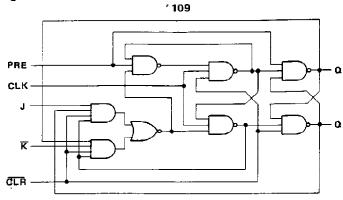
logic symbol‡



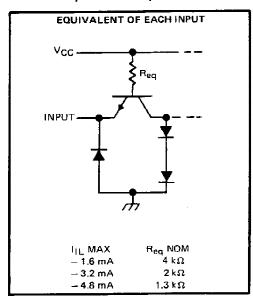
[‡]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

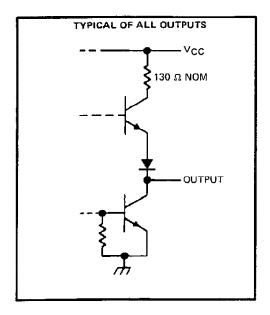
logic diagram (positive logic)

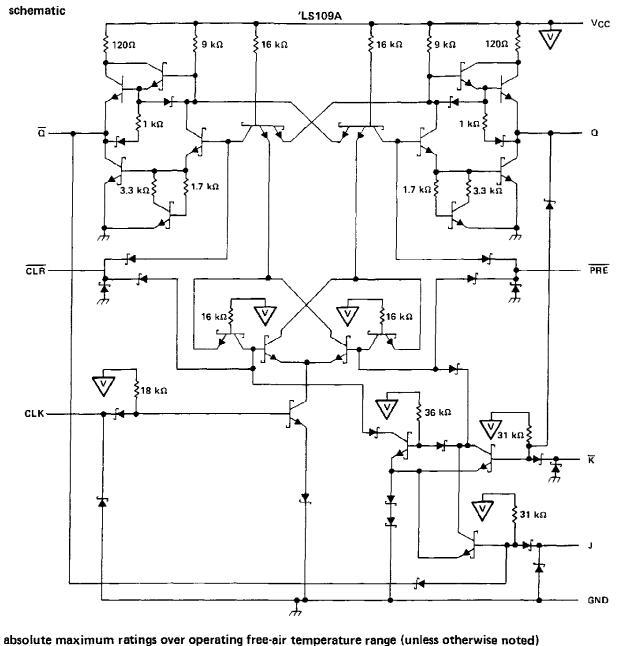


schematics of inputs and outputs



109





Supply voltage, VCC (see Note 1)	***************************************	7 V
Input voltage: '109	<u> </u>	5.5 V
'LS109A		
Operating free-air temperature range:	SN54'	- 55°C to 125°C
·	SN74'	0°C to 70°C
Storage temperature range	***************************************	- 65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



SN54109, SN74109 DUAL J-K POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

recommended operating conditions

		-		1	UNIT				
			MIN	MOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage		2			2			V
٧ıL	Low-level input voltage			.,	8.0			0.8	V
ІОН	High-level output current				- 0.8			- 0.8	mA
IOL	Low-level output current				16			16	mA
	Pulse duration	CLK high or low	20			20			
tw.	Fuise duration	PRE or CLR low	20			20		T	ns
tsu	Input setup time before CLK 1	·	10			10			ns
t _{h_}	Input hold time-data after CLK1		6			6			ns
TΑ	Operating free-air temperature		~ 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PAR.	AMETER		TEST CONDITI	onet		SN5410	9		SN7410	9	UNIT
1211	AIVIETEIS !		TEBT CONDITI		MIN	TYP‡	MAX	MIN	TYP‡	MAX	DIVIT
VIK		V _{CC} = MIN,	= - 12 mA				- 1.5			- 1.5	V
Vон		V _{CC} = MIN, I _{OH} = - 0.8 mA	V _{IH} = 2 V,	V _{IL} ≈ 0.8 V,	2.4	3,4		2.4	3.4		v
VOL		V _{CC} = MIN, I _{OL} = 16 mA	V _{IH} = 2 V,	V _{IL} = 0.8 V,		0.2	0.4		0.2	0.4	٧
11		V _{CC} = MAX,	V _I = 5.5 V				1		·	1	mA
	J or K						40			40	
1	CLR	V _{CC} = MAX,	V. ~ 2.4.V				160			160	_
НІ	PRE or CLK	4GC - MIAA,	v ₁ - 2.4 v				80			80	μА
	Jor \overline{K}						- 1.6			- 1.6	
1	CLR1	V _{CC} = MAX,	V. = 0.4 W				- 4.8			- 4.8	mΑ
'IL	PRE¶	OCC - MAX,	V = 0.4 V				- 3.2			- 3.2	
	CLK		-	<u></u>			- 3.2			-3.2	
los §		V _{CC} = MAX			- 30		- 85	- 30	* ***	- 85	mA
ICC#		V _{CC} = MAX,	See Note 2		T	9	15		9	15	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: With all outputs open. ICC is measured with the Q and Q outputs high in turn. At the time of measurement, the clock input is grounded,

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
fmax				25	33		MHz
tPLH	PRE	Q			10	15	ns
₹₽HL		ā			23	35	ns
^t PLH	CLR	ত্র	$R_L = 400 \Omega$, $C_L = 15 \rho F$		10	15	ns
tpHL	0211	a			17	25	ns
TPLH	CLK	QorQ			10	16	ns
tpHL_	OEK .	4314			18	28	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25 \,^{\circ}\text{C}$.

[§] Not more than one output should be shorted at a time.

¹ Clear is tested with preset high and preset is tested with clear high.

[#] Average per flip-flop.

SN54LS109A, SN74LS109A DUAL J-K POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

recommended operating conditions

			s	N54LS1	09A	SI	N74LS1	A90	118117
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
v _{CC}	Supply voltage		4.5	5	5.5	4.75	5	5.25	٧
v_{lH}	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.7			0.8	V
ТОН	High-level output current				- 0.4		••	- 0.4	mA
IOL	Low-level output current				4			8	mA
fclock	Clock frequency		0		25	0		25	MHz
	Dulan dunain	CLK high	25			25	_		
t _w	Pulse duration	PRE or CLR low	25			25			ns
	Beautiful before CLV 4	High-level data	35			35			
t _{su}	Setup time before CLK †	Low-level data	25			25			ns
th	Hold time-data after CLK †		5			5			ns
TA	Operating free-air temperature		- 55	*	125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITION	uet	SN	154LS10)9A	SN	דומט		
FARAINE I ER	1	TEST CONDITIO	49.	MIN	TYP#	MAX	MIN	TYP#	MAX	וואטן
Vik	VCC - MIN,	I _I = - 18 mA	-			– 1.5		_	_ 1.5	V
VOH	V _{CC} = MIN, I _{OH} = - 0.4 mA	V _{IH} = 2 V,	V _{IL} = MAX,	2.5	3.4		2.7	3.4		V
	V _{CC} = MIN, I _{OL} = 4 mA	VIL = MAX,	V _{IH} = 2 V,		0.25	0,4		0.25	0.4	V
VOL	V _{CC} = MIN, I _{OL} = 8 mA	VIL = MAX,	V _{1H} = 2 V,					0.35	0.5	\ \ \
J, K or CLK	Vcc = MAX,	V ₁ = 7 V				0.1			0.1	_^
CLR or PRE	ACC - MINY	- V - Y V				0.2			0.2	mA
J, R or CLK	V _{CC} = MAX,	V ₁ = 2.7 V				20			20	
TH CLR or PRE	7 400 - 14122	V - 2.7 V				40			40	μΑ
J, K or CLK	VCC = MAX,	V _I = 0.4 V				- 0.4			- 0.4	
CLR or PRE	YCC - WAX,	V - 0.4 V				- 0.8			- 0.8	mA
OS§	VCC = MAX,	See Note 4	_	- 20	_	100	- 20		- 100	mA
ICC (Total)	V _{CC} = MAX,	See Note 2			4	8		4	8	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions,

NOTE 2: With all outputs open, ICC is measured with the Q and Q outputs high in turn. At the time of measurement, the clock input is grounded.

NOTE 4: For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with V_O = 2.25 V and 2.125 V for the 54 family and the 74 family, respectively with the minimum and maximum limits reduced to one half of their stated values.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	мах	UNIT
f _{max}				25	33		MHz
^t PLH	CLR, PRE	Q or Q	$R_L = 2 k\Omega$, $C_L = 15 pF$		13	25	ns
^t PHL_	or CLK				25	40	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C. §Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.





24-Aug-2018

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/30109BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30109BEA	Samples
JM38510/30109BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30109BFA	Samples
JM38510/30109BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30109BFA	Samples
M38510/30109BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30109BEA	Samples
M38510/30109BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30109BEA	Samples
M38510/30109BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30109BFA	Samples
M38510/30109BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30109BFA	Samples
SN54LS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS109AJ	Samples
SN54LS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS109AJ	Samples
SN74LS109AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS109A	Samples
SN74LS109AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS109A	Samples
SN74LS109ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS109A	Samples
SN74LS109ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS109A	Samples
SN74LS109ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS109A	Samples
SN74LS109ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS109A	Samples
SN74LS109AN	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS109AN	Samples
SN74LS109AN	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS109AN	Samples



PACKAGE OPTION ADDENDUM

24-Aug-2018

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74LS109ANE4	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS109AN	Samples
SN74LS109ANE4	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS109AN	Samples
SN74LS109ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS109A	Samples
SN74LS109ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS109A	Samples
SNJ54LS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS109AJ	Samples
SNJ54LS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS109AJ	Samples
SNJ54LS109AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS109AW	Samples
SNJ54LS109AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS109AW	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



PACKAGE OPTION ADDENDUM

24-Aug-2018

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54LS109A, SN74LS109A:

Catalog: SN74LS109A

Military: SN54LS109A

NOTE: Qualified Version Definitions:

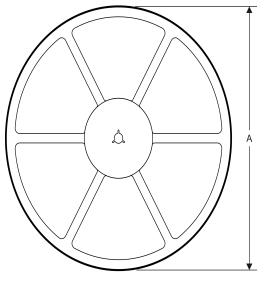
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

14-Jul-2012 www.ti.com

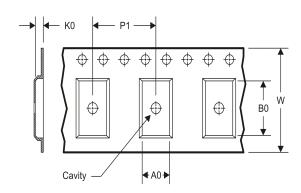
TAPE AND REEL INFORMATION

REEL DIMENSIONS





TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS109ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS109ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 14-Jul-2012



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS109ADR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS109ANSR	SO	NS	16	2000	367.0	367.0	38.0

IMPORTANT NOTICE

Texas Instruments Incorporated (TI) reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete.

TI's published terms of sale for semiconductor products (http://www.ti.com/sc/docs/stdterms.htm) apply to the sale of packaged integrated circuit products that TI has qualified and released to market. Additional terms may apply to the use or sale of other types of TI products and services.

Reproduction of significant portions of TI information in TI data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such reproduced documentation. Information of third parties may be subject to additional restrictions. Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyers and others who are developing systems that incorporate TI products (collectively, "Designers") understand and agree that Designers remain responsible for using their independent analysis, evaluation and judgment in designing their applications and that Designers have full and exclusive responsibility to assure the safety of Designers' applications and compliance of their applications (and of all TI products used in or for Designers' applications) with all applicable regulations, laws and other applicable requirements. Designer represents that, with respect to their applications, Designer has all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. Designer agrees that prior to using or distributing any applications that include TI products, Designer will thoroughly test such applications and the functionality of such TI products as used in such applications.

TI's provision of technical, application or other design advice, quality characterization, reliability data or other services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using TI Resources in any way, Designer (individually or, if Designer is acting on behalf of a company, Designer's company) agrees to use any particular TI Resource solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

Designer is authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY DESIGNER AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

Unless TI has explicitly designated an individual product as meeting the requirements of a particular industry standard (e.g., ISO/TS 16949 and ISO 26262), TI is not responsible for any failure to meet such industry standard requirements.

Where TI specifically promotes products as facilitating functional safety or as compliant with industry functional safety standards, such products are intended to help enable customers to design and create their own applications that meet applicable functional safety standards and requirements. Using products in an application does not by itself establish any safety features in the application. Designers must ensure compliance with safety-related requirements and standards applicable to their applications. Designer may not use any TI products in life-critical medical equipment unless authorized officers of the parties have executed a special contract specifically governing such use. Life-critical medical equipment is medical equipment where failure of such equipment would cause serious bodily injury or death (e.g., life support, pacemakers, defibrillators, heart pumps, neurostimulators, and implantables). Such equipment includes, without limitation, all medical devices identified by the U.S. Food and Drug Administration as Class III devices and equivalent classifications outside the U.S.

TI may expressly designate certain products as completing a particular qualification (e.g., Q100, Military Grade, or Enhanced Product). Designers agree that it has the necessary expertise to select the product with the appropriate qualification designation for their applications and that proper product selection is at Designers' own risk. Designers are solely responsible for compliance with all legal and regulatory requirements in connection with such selection.

Designer will fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of Designer's non-compliance with the terms and provisions of this Notice.